# Low-Voltage CMOS Hex Inverter with Open Drain Outputs

# With 5 V - Tolerant Inputs

The MC74LCX06 is a high performance hex inverter operating from a 2.3 V to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers. These LCX devices have open drain outputs which provide the ability to set output levels, or do active–HIGH AND or active–LOW OR functions. A  $V_{\rm I}$  specification of 5.5 V allows MC74LCX06 inputs to be safely driven from 5.0 V devices.

## **Features**

- Designed for 2.3 V to 3.6 V V<sub>CC</sub> Operation
- 5.0 V Tolerant Inputs/Outputs
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Output Sink Capability
- Near Zero Static Supply Current (10 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- Wired-OR, Wired-AND
- Output Level Can Be Set Externally Without Affecting Speed of Device
- Functionally Compatible with LCX05
- ESD Performance: Human Body Model >1500 V; Machine Model >200 V
- Pb-Free Packages are Available\*

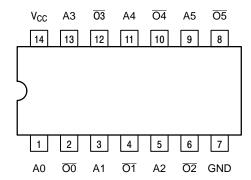


Figure 1. Pinout: 14-Lead (Top View)

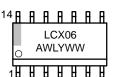


http://onsemi.com

# MARKING DIAGRAMS

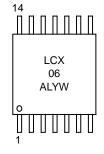


SOIC-14 D SUFFIX CASE 751A



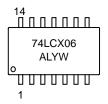


TSSOP-14 DT SUFFIX CASE 948G





SOEIAJ-14 M SUFFIX CASE 965



A = Assembly Location

WL, L = Wafer Lot Y = Year WW, W = Work Week

# ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

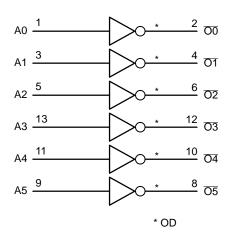


Figure 2. Logic Diagram

# **Table 1. PIN NAMES**

Pins	Function
An	Data Inputs
On	Outputs

# **Table 2. TRUTH TABLE**

An	<del>On</del>
L	Z
H	L

# **MAXIMUM RATINGS**

Symbol	Parameter	Value	Condition	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	$-0.5 \le V_1 \le +7.0$		V
Vo	DC Output Voltage	$-0.5 \le V_O \le +7.0$	Output in HIGH or LOW State (Note 1)	V
I <sub>IK</sub>	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA
I <sub>OK</sub>	DC Output Diode Current	-50	V <sub>O</sub> < GND	mA
		+50	V <sub>O</sub> > V <sub>CC</sub>	mA
I <sub>O</sub>	DC Output/Sink Current	+50		mA
I <sub>CC</sub>	DC Supply Current Per Supply Pin	±100		mA
I <sub>GND</sub>	DC Ground Current Per Ground Pin	±100		mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150		°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. I<sub>O</sub> absolute maximum rating must be observed.

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74LCX06D	SOIC-14	50 Units / Rail
MC74LCX06DG	SOIC-14 (Pb-Free)	50 Units / Rail
MC74LCX06DR2	SOIC-14	2500 / Tape & Reel
MC74LCX06DR2G	SOIC-14 (Pb-Free)	2500 / Tape & Reel
MC74LCX06DT	TSSOP-14*	96 Units / Rail
MC74LCX06DTR2	TSSOP-14*	2500 / Tape & Reel
MC74LCX06M	SOEIAJ-14	50 Units / Rail
MC74LCX06MEL	SOEIAJ-14	2000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. \*This package is inherently Pb-Free.

# **RECOMMENDED OPERATING CONDITIONS**

Symbol	Param	neter	Min	Тур	Max	Unit
V <sub>CC</sub>	Supply Voltage	Operating Data Retention Only	2.0 1.5	2.5, 3.3 2.5, 3.3	3.6 3.6	V
VI	Input Voltage		0		5.5	V
Vo	Output Voltage	(HIGH or LOW State)	0		V <sub>CC</sub>	V
I <sub>OL</sub>	LOW Level Output Current Sink	$V_{CC} = 3.0 \text{ V} - 3.6 \text{ V}$ $V_{CC} = 2.7 \text{ V} - 3.0 \text{ V}$ $V_{CC} = 2.3 \text{ V} - 2.7 \text{ V}$			+24 +12 +8	mA
T <sub>A</sub>	Operating Free–Air Temperature		-40		+85	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate, VIN	from 0.8 V to 2.0 V, V <sub>CC</sub> = 3.0 V	0		10	ns/V

# **DC ELECTRICAL CHARACTERISTICS** $(T_A = -40^{\circ}C \text{ to } +85^{\circ}C)$

Symbol	Characteristic	Condition	Min	Max	Unit
V <sub>IH</sub>	HIGH Level Input Voltage (Note 2)	2.3 V ≤ V <sub>CC</sub> ≤ 2.7 V	1.7		V
		2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V	2.0	1	
V <sub>IL</sub>	LOW Level Input Voltage (Note 2)	2.3 V ≤ V <sub>CC</sub> ≤ 2.7 V		0.7	V
		2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V		0.8	1
V <sub>OL</sub>	LOW Level Output Voltage	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OL} = 100 \mu\text{A}$		0.2	V
		$V_{CC} = 2.3 \text{ V; } I_{OL} = 8 \text{ mA}$		0.3	
		V <sub>CC</sub> = 2.7 V; I <sub>OL</sub> = 12 mA		0.4	1
		$V_{CC} = 3.0 \text{ V}; I_{OL} = 16 \text{ mA}$		0.4	1
		$V_{CC} = 3.0 \text{ V}; I_{OL} = 24 \text{ mA}$		0.55	1
I <sub>I</sub>	Input Leakage Current	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; 0 \text{ V} \le \text{V}_{I} \le 5.5 \text{ V}$		±5.0	μΑ
I <sub>OFF</sub>	Power-Off Leakage Current	$V_{CC} = 0 \text{ V}; V_{I} \text{ or } V_{O} = 5.5 \text{ V}$		10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{ V}_{I} = \text{GND or V}_{CC}$		10	μΑ
		$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \ 3.6 \le \text{V}_{I} \le 5.5 \text{ V}$		±10	μΑ
$\Delta I_{CC}$	Increase in I <sub>CC</sub> per Input	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}$ One Input at $\text{V}_{IH} = \text{V}_{CC} - 0.6 \text{ V}$		500	μΑ

<sup>2.</sup> These values of V<sub>I</sub> are used to test DC electrical characteristics only.

# AC ELECTRICAL CHARACTERISTICS ( $T_A = -40$ °C to +85°C)

			V ± 0.3 V 50 pF	V <sub>CC</sub> =	2.7 V 50 pF	V <sub>CC</sub> = 2.5 C <sub>L</sub> = 3	V ± 0.2 V 30 pF	
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Unit
t <sub>PLZ</sub> t <sub>PZL</sub>	Propagation Delay Input to Output	0.8 0.8	3.7 3.7	1.0 1.0	4.1 4.1	0.8 0.8	3.5 3.5	ns ns

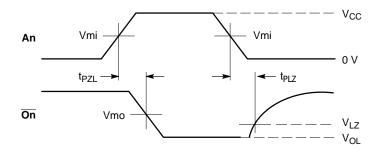
# DYNAMIC SWITCHING CHARACTERISTICS (T<sub>A</sub> = $+25^{\circ}$ C)

Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V <sub>OLP</sub>	Dynamic LOW Peak Voltage (Note 3)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$ $V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$		0.9 0.7		V
V <sub>OLV</sub>	Dynamic LOW Valley Voltage (Note 3)	$V_{CC}$ = 3.3 V, $C_L$ = 50 pF, $V_{IH}$ = 3.3 V, $V_{IL}$ = 0 V $V_{CC}$ = 2.5 V, $C_L$ = 30 pF, $V_{IH}$ = 2.5 V, $V_{IL}$ = 0 V		-0.8 -0.6		V

<sup>3.</sup> Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

# **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	7	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, $V_{CC} = 3.3 \text{ V}$ , $V_{I} = 0 \text{ V}$ or $V_{CC}$	25	pF

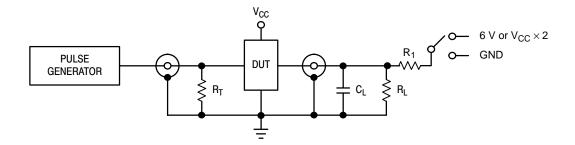


**PROPAGATION DELAYS** 

 $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$ 

Table 3. AC WAVEFORMS

	V <sub>CC</sub>					
Symbol	3.3 V ± 0.3 V	2.7 V	2.5 V $\pm$ 0.2 V			
V <sub>mi</sub>	1.5 V	1.5 V	V <sub>CC</sub> / 2			
V <sub>mo</sub>	1.5 V	1.5 V	V <sub>CC</sub> / 2			
$V_{LZ}$	V <sub>OL</sub> + 0.3 V	V <sub>OL</sub> + 0.3 V	V <sub>OL</sub> + 0.15 V			



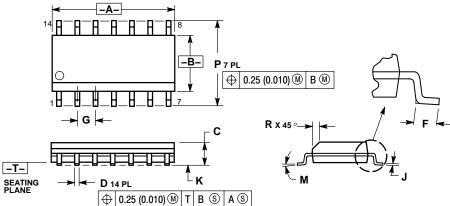
**Table 4. TEST CIRCUIT** 

TEST	SWITCH		
t <sub>PZL</sub> , t <sub>PLZ</sub>	6 V		
Open Collector/Drain t <sub>PLH</sub> and t <sub>PHL</sub>	6 V		
t <sub>PZH</sub> , t <sub>PHZ</sub>	GND		

 $C_L$  = 50 pF at  $V_{CC}$  = 3.3  $\pm$  0.3 V or equivalent (includes jig and probe capacitance)  $C_L$  = 30 pF at  $V_{CC}$  = 2.5  $\pm$  0.2 V or equivalent (includes jig and probe capacitance)  $R_L$  =  $R_1$  = 500  $\Omega$  or equivalent  $R_T$  =  $Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

## PACKAGE DIMENSIONS

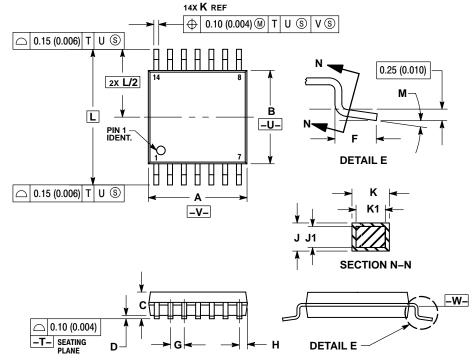
# SOIC-14 **D SUFFIX** CASE 751A-03 ISSUE G



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
- 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE
  DAMBAR PROTRUSION. ALLOWABLE
  DAMBAR PROTRUSION SHALL BE 0.127
  (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
7	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
М	0 °	7°	0 °	7°
Р	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

TSSOP-14 **DT SUFFIX** CASE 948G-01 **ISSUE O** 



- OTES.

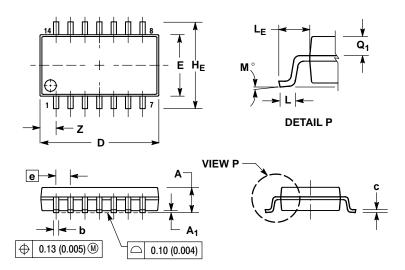
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.
- 2. OMTHOLIUM DIMELTION, MILEUITETT.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH,
  PROTRUSIONS OR GATE BURRS. MOLD FLASH
  OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED
- PROTRUSION SHALL NOT EXCEED
  0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN
  EXCESS OF THE K DIMENSION AT MAXIMUM
  MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
  DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

# PACKAGE DIMENSIONS

SOEIAJ-14 **M SUFFIX** CASE 965-01 **ISSUE O** 



#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
   DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
  THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 ( 0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10°	0 °	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z		1.42		0.056

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